# Materials Declaration

| | |
|---|---|
| **Package** | MQFP |
| **Body Size** | 10 X 10 |
| **LeadCount** | 52 |
| **Option** | Pb-Free |

**Molding Compound**

| Item | % of Compound | Weight (g) | PPM |
|---|---|---|---|
| Epoxy resin | 8 | 2.20 E-02 | 42416 |
| SiO2 Filler | 86 | 2.36 E-01 | 455972 |
| Phenol Resin | 5 | 1.37 E-02 | 26510 |
| Antimony_Sb2O3 | 0.4 | 1.10 E-03 | 2121 |
| Brominated Resin | 0.4 | 1.10 E-03 | 2121 |
| Carbon Black | 0.2 | 5.49 E-04 | 1060 |

**Molding Compound**

| Item | PPM | Method |
|---|---|---|
| Pb | <2.0 | EPA method #3052 (ICPAES) |
| Cd | <2.0 | BS EN 1122:2001B (ICPaes) |
| Hg | <2.0 | Mercury Analyser |
| Cr+6 | <2.0 | EPA method #3060A(UV) |
| PBB | ND | SGS In-House Method |
| PBDE | ND | SGS In-House Method |

**Leadframe**

| Item | % of Leadframe | Weight (g) | PPM |
|---|---|---|---|
| Cu | 96.2 | 1.54 E-01 | 296307 |
| Ni | 3 | 4.79 E-03 | 9240 |
| Si | 0.65 | 1.04 E-03 | 2002 |
| Mg | 0.15 | 2.39 E-04 | 462 |

**Die Attach Paste**

| Item | PPM | Method |
|---|---|---|
| Pb | <5.0 | ICP-AES |
| Cd | <5.0 | ICP-AES |
| Hg | <5.0 | ICP-AES |
| Cr+6 | <5.0 | EPA method 7196A & EPA 3060A |

**Internal Leadframe Plating**

| | % of Plating | Weight (g) | PPM |
|---|---|---|---|
| Ag | 100 | 1.99 E-03 | 3836 |

**External Leadframe Plating**

| Item | % of Plating | Weight (g) | PPM |
|---|---|---|---|
| Sn | 100 | 1.00 E-02 | 19361 |

**Bond Wires**

| | % of Wire | Weight (g) | PPM |
|---|---|---|---|
| Au | 99.99 | 1.62 E-03 | 3122 |

**Chip**

| | % of Chip | Weight (g) | PPM |
|---|---|---|---|
| Si | 100 | 6.52 E-02 | 125754 |

**Die Attach**

| Item | % of Die Attach | Weight (g) | PPM |
|---|---|---|---|
| Resin | 26 | 1.31 E-03 | 2526 |
| Ag Filler | 74 | 3.72 E-03 | 7190 |

**Package Totals**

| Weight (g) | PPM |
|---|---|
| **5.18 E-01** | 1000000 |

STS-S-B

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability tc any inaccuracy of such information.

# Materials Declaration

| | |
|---|---|
| **Package** | MQFP |
| **Body Size** | 10 X 10 |
| **LeadCount** | 52 |
| **Option** | Sn/Pb |

**Molding Compound**

| Item | % of Compound | Weight (g) | PPM |
|---|---|---|---|
| Epoxy resin | 8 | 2.20 E-02 | 42416 |
| SiO2 Filler | 86 | 2.36 E-01 | 455972 |
| Phenol Resin | 5 | 1.37 E-02 | 26510 |
| Antimony_Sb2O3 | 0.4 | 1.10 E-03 | 2121 |
| Brominated Resin | 0.4 | 1.10 E-03 | 2121 |
| Carbon Black | 0.2 | 5.49 E-04 | 1060 |

**Leadframe**

| Item | % of Leadframe | Weight (g) | PPM |
|---|---|---|---|
| Cu | 96.2 | 1.54 E-01 | 296307 |
| Ni | 3 | 4.79 E-03 | 9240 |
| Si | 0.65 | 1.04 E-03 | 2002 |
| Mg | 0.15 | 2.39 E-04 | 462 |

**Internal Leadframe Plating**

| | % of Plating | Weight (g) | PPM |
|---|---|---|---|
| Ag | 100 | 1.99 E-03 | 3836 |

**External Leadframe Plating**

| Item | % of Plating | Weight (g) | PPM |
|---|---|---|---|
| Sn | 85 | 8.53 E-03 | 16457 |
| Pb | 15 | 1.50 E-03 | 2904 |

**Bond Wires**

| | % of Wire | Weight (g) | PPM |
|---|---|---|---|
| Au | 99.99 | 1.62 E-03 | 3122 |

**Chip**

| | % of Chip | Weight (g) | PPM |
|---|---|---|---|
| Si | 100 | 6.52 E-02 | 125754 |

**Die Attach**

| Item | % of Die Attach | Weight (g) | PPM |
|---|---|---|---|
| Resin | 26 | 1.31 E-03 | 2526 |
| Ag Filler | 74 | 3.72 E-03 | 7190 |

**Package Totals**

| Weight (g) | PPM |
|---|---|
| **5.18 E-01** | 1000000 |

**Molding Compound**

| Item | PPM | Method |
|---|---|---|
| Pb | <2.0 | EPA method #3052 (ICP-AES) |
| Cd | <2.0 | BS EN 1122:2001B (ICP-AES) |
| Hg | <2.0 | Mercury Analyser |
| Cr+6 | <2.0 | EPA method #3060A(UV) |
| PBB | ND | SGS In-House Method |
| PBDE | ND | SGS In-House Method |

**Die Attach Paste**

| Item | PPM | Method |
|---|---|---|
| Pb | <5.0 | ICP-AES |
| Cd | <5.0 | ICP-AES |
| Hg | <5.0 | ICP-AES |
| Cr+6 | <5.0 | EPA method 7196A & EPA 3060A |

STS-S-A

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